



Material Content Data Sheet



Sales Product Name		BTS3125TF		Issued		1. August 2018		
MA#		MA001328794						
Package		PG-TO252-3-313		Weight*		316.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.677	0.21	0.21	2138	2138
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		140	
	non noble metal	iron	7439-89-6	0.147	0.05		465	
	non noble metal	copper	7440-50-8	147.096	46.44	46.50	464440	465045
	non noble metal	aluminium	7429-90-5	0.150	0.05	0.05	474	474
wire	non noble metal	aluminium	7429-90-5	0.150	0.05	0.05	474	474
encapsulation	organic material	carbon black	1333-86-4	1.433	0.45		4524	
	plastics	epoxy resin	-	25.076	7.92		79174	
	inorganic material	silicondioxide	60676-86-0	116.783	36.87	45.24	368727	452425
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11809	11809
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4485	4496
solder	non noble metal	tin	7440-31-5	0.019	0.01		60	
	noble metal	silver	7440-22-4	0.024	0.01		75	
	non noble metal	lead	7439-92-1	0.902	0.28	0.30	2849	2984
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60550	60629
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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